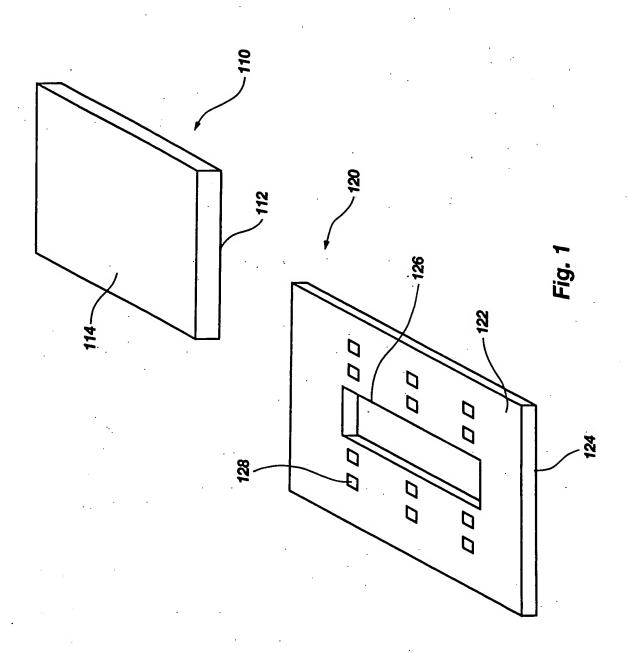
1/6



## TITLE: BUMPED DIE AND WIRE BONDED BOARD-ON-CHIP PACKAGE Inventor: Larry D. Kinsman Docket No.: 4585.3US



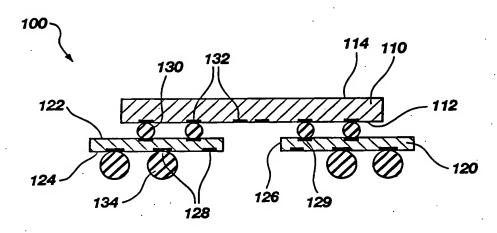
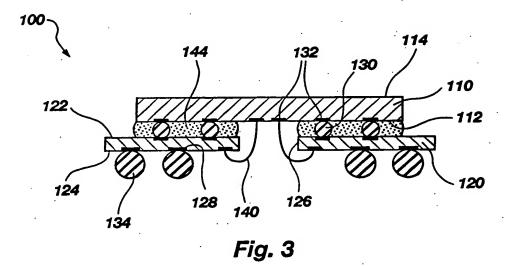


Fig. 2



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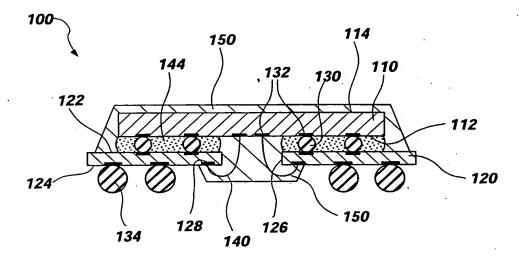
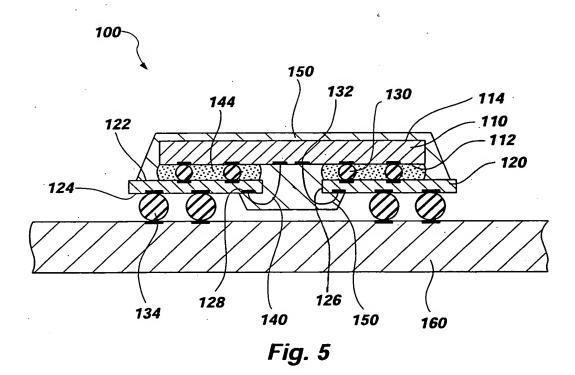
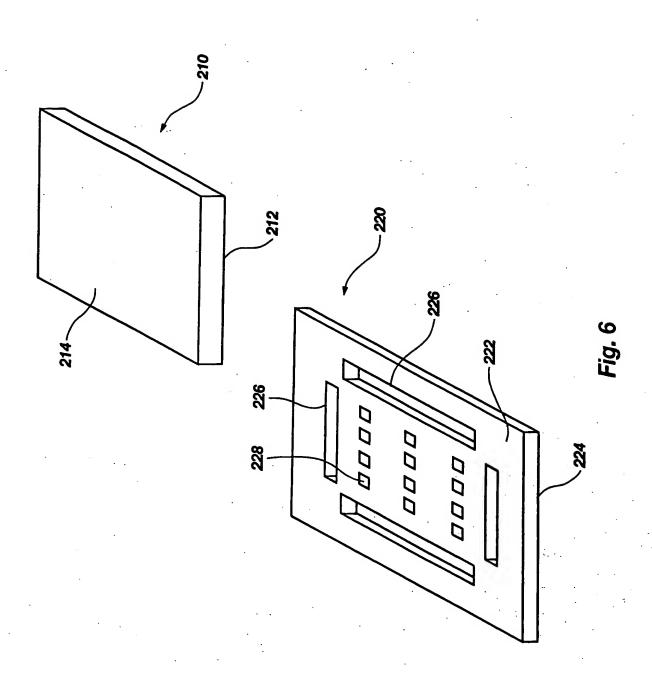


Fig. 4



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## TITLE: BUMPED DIE AND WIRE BONDED BOARD-ON-CHIP PACKAGE Inventor: Larry D. Kinsman Docket No.: 4585.3US

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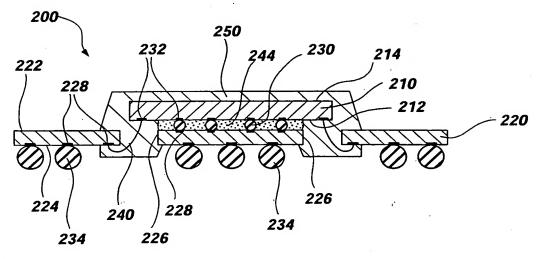
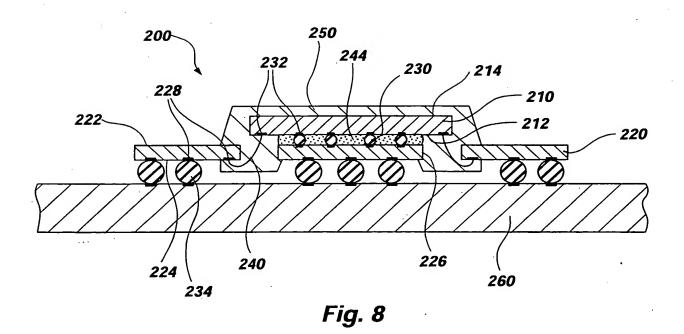


Fig. 7



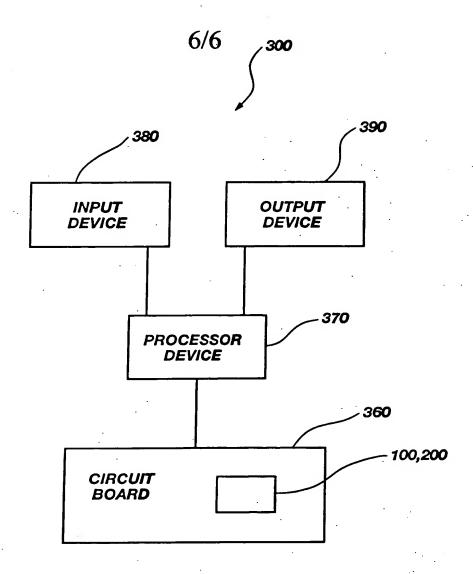


Fig. 9